ABSTRACT

A UV irradiating portion 12 is provided with multiple UV light emitting diodes 21 arranged on a base plate 20 which is in a position corresponding to a semiconductor wafer attached with a protective sheet S through a UV curable adhesive layer 18 as an irradiation receiving body. The light emitting diodes 21 are arranged at intervals of substantially equal spaces along the direction substantially perpendicular to the relative movement direction with a wafer W. And, the light emitting diodes 21 in each row are arranged to have substantially the same peak wavelength, while the peak wavelengths of the light emitting diodes 21 in the adjacent rows are arranged to be not necessarily the same.